



New Sinter pastes designed for applications like lead-frame die-attach:

- Optimized chemical composition with no solvents added
- Ensures optimal wetting and bonding
- Pressureless sintering material with 6 months shelf and 8h+ pot-life
- Sintering temperatures 220°C to 250°C, in Air, N₂ and Ar

Properties:

- High reproduceability
- Shear strength: up to 80 MPa
- Heat conduction: >300 W/mK
- Electric Resistance: 3mΩ*cm

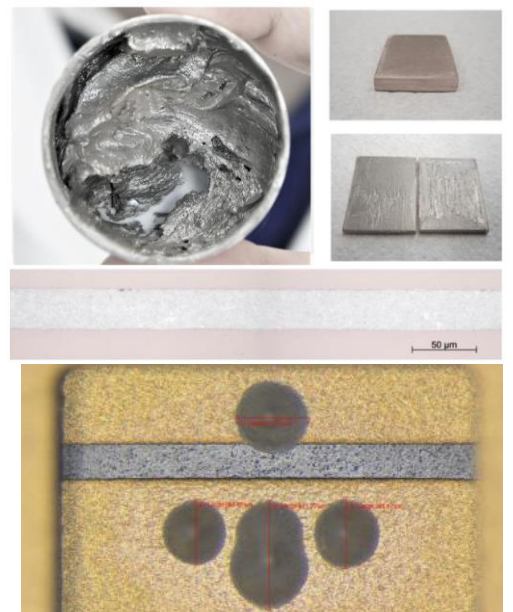
Technical Data:

- Typical viscosity of 30Pa*s; 5 rpm
- Typical silver content of ~92%
- Nontoxic and ROHS compliant

Applicable with standard printing methods (stencil , screen printing)

Processing data:

- Placement should result in a BLT after sintering of 25-30µm; printed paste 50-100 µm
- Profile: RT – 5K/min to 90°C – 10min holding time – 5K/min to 250°C / 30-45min holding time* – moderate cool down
- *Holding time depends on thermal mass of the modules to be sintered
- *Holding temperature may be reduced down to 220°C resulting in longer holding times



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